

ABSTRACT

WAFER PROCESSING METHOD

A wafer processing method includes: an alignment step of capturing the front surface side of the wafer through a sealing material by an infrared imaging unit from the front surface side of the wafer, detecting an alignment mark, and detecting the division line to be laser processed based on the alignment mark; and a dividing step of emitting a laser beam of such a wavelength as to be absorbed in the sealing material along the division lines from the front surface side of the wafer, and dividing the wafer by ablation processing into individual device chips each of which has its front surface and four side surfaces surrounded by the sealing material.

(Figure 5)